

1. Part No. Expression:

CMT03 - 330 - RA - □□

(a) (b) (c) (d)(e) (f)

(a) Series Code

(b) Dimension Code

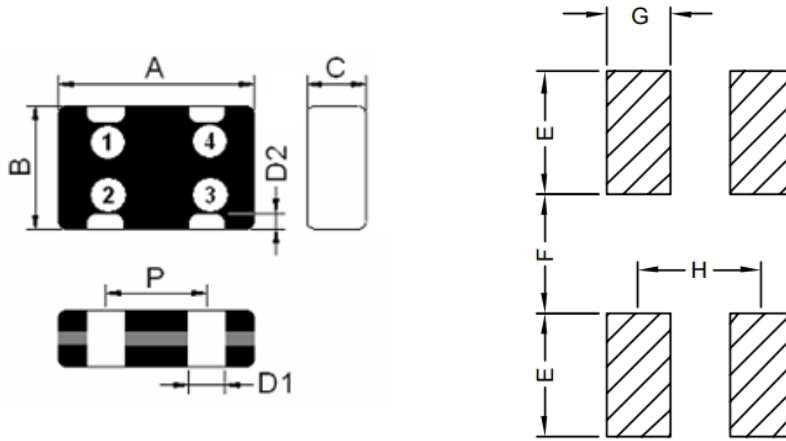
(c) Impedance Code

(d) Packaging Code

(e) Current Rating Code

(f) 10: Standard Code , 11-99: Internal Control Code

2. Configuration & Dimensions:



Recommended PCB layout

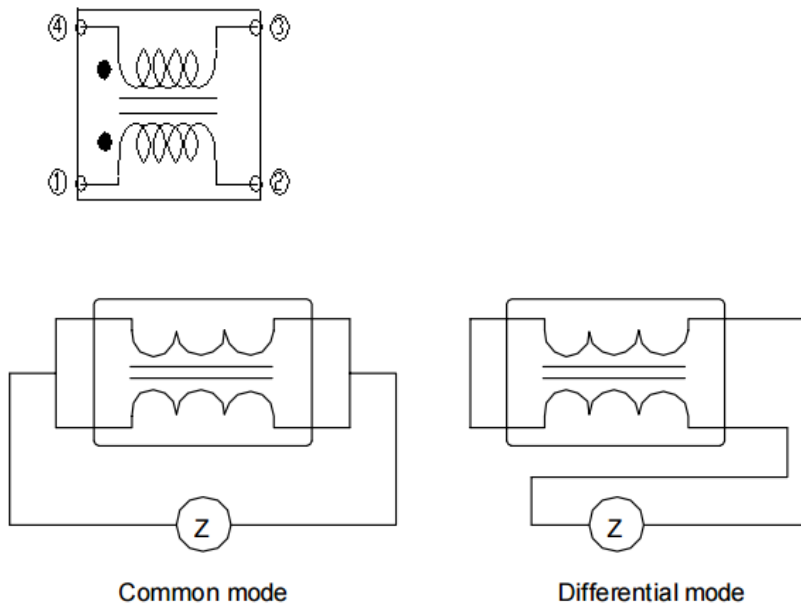
Unit: mm

A	B	C	P	D1	D2	E	F	G	H
0.85±0.05	0.65±0.05	0.40±0.05	0.50±0.10	0.27±0.10	0.20+0.05/-0.1	0.25 - 0.35	0.25 - 0.35	0.25 - 0.35	0.5

NOTE: Specifications subject to change without notice. Please check our website for latest information.



3. Schematic:



4. General Specification:

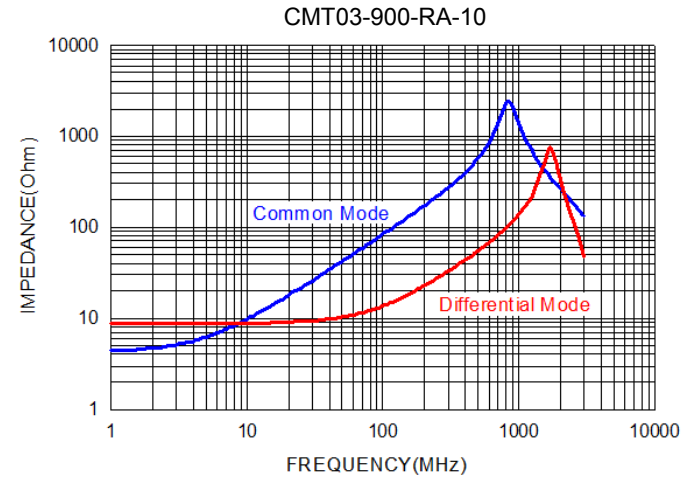
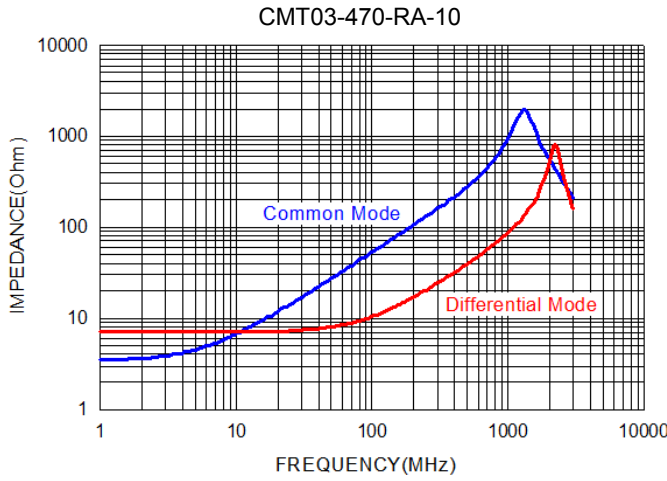
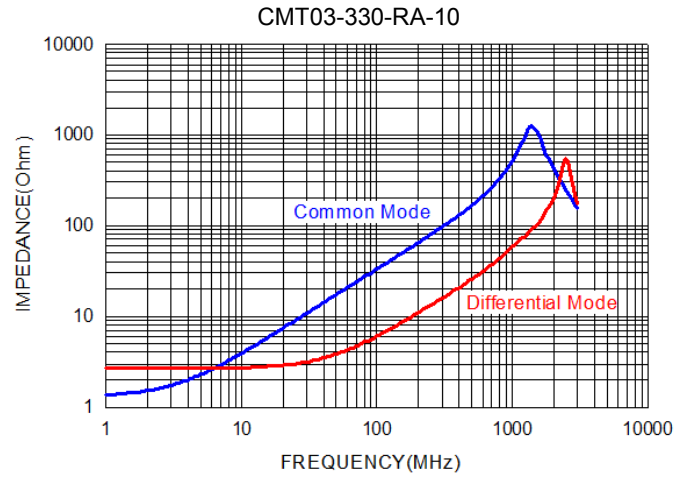
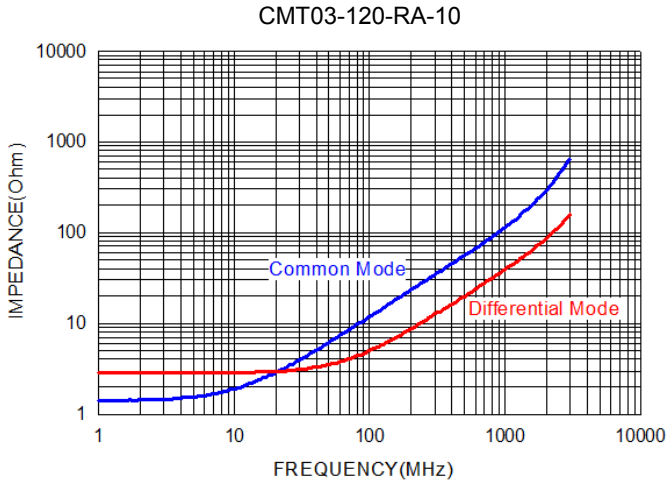
- (a) Operating Temp. : -40°C to +85°C
- (b) Storage Condition (Component in its packaging)
- i) Temperature: Less than 40°C
 - ii) Humidity : 60% RH

5. Electrical Characteristics:

Part Number	Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) Max.	IDC (mA) Max.	Rated Voltage (Vdc) Max.	Insulation Resistance (M Ω) Min.
CMT03-120-RA-10	12 \pm 5 Ω	100	2.5	130	5	100
CMT03-330-RA-10	33 \pm 20%	100	2.5	100	5	100
CMT03-470-RA-10	47 \pm 20%	100	5.0	100	5	100
CMT03-900-RA-10	90 \pm 20%	100	6.5	100	5	100

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6. Characteristic Curves:



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7. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

Note: If wave soldering is used, there will be some risk.

Reflow soldering temperatures below 240°C, there will be non-wetting risk

7-1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

7-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.

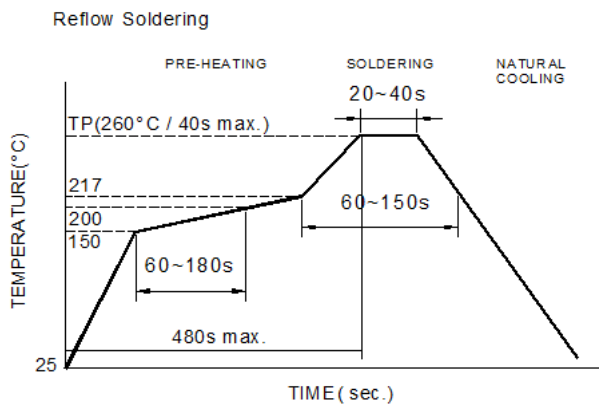


Figure 1. : Re-flow Soldering time
3 times max

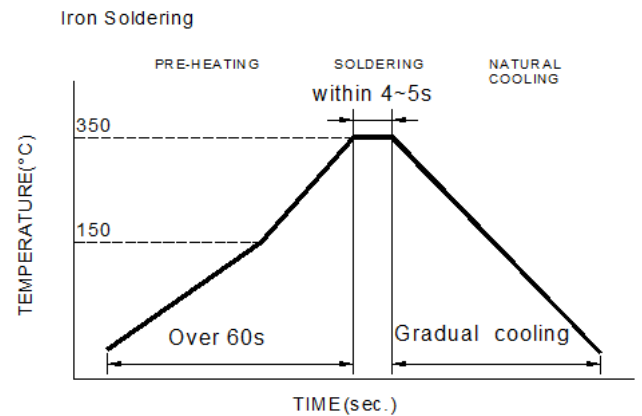
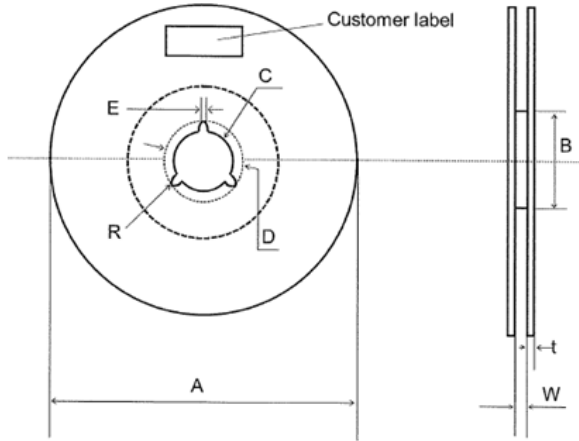


Figure 2. : Iron Soldering time
1 times max

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8. Packaging Information:

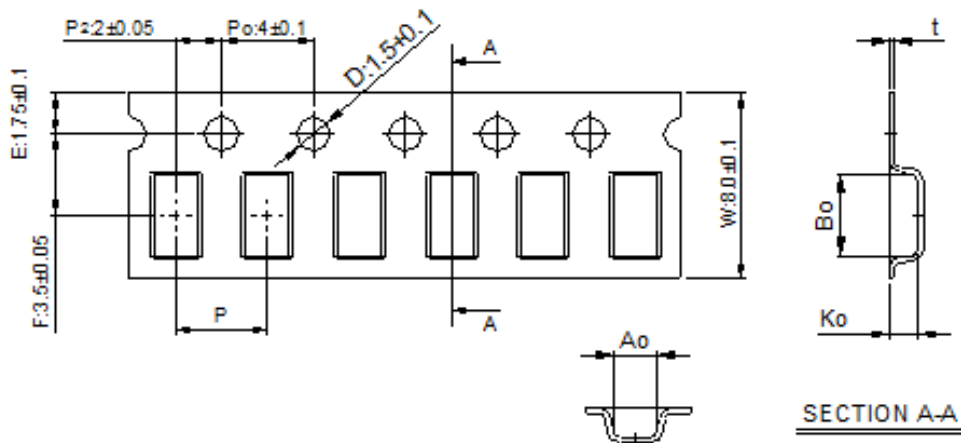
8-1 Reel Dimension



Unit: mm

ϕA	ϕB	ϕC	ϕD	E	W	t	R
178±2.0	50 Min.	13±0.2	21±0.8	2.0±0.5	10±1.5	2.5 Max.	1.0

8-2 Tape Dimension

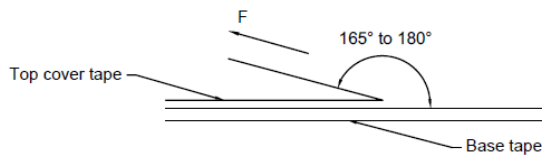


Size	B_0 (mm)	A_0 (mm)	K_0 (mm)	P (mm)	t (mm)
CMT03	0.95±0.05	0.75±0.05	0.55±0.05	4.0±0.10	0.3 max

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8-3 Packaging Quantity

Chip Size	CMT03
Chip /Reel	10,000
Inner box	50,000
Middle box	250,000
Carton	500,000

8-4 Tearing Off Force

The force for tearing off cover tape is 15 to 85 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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